INTRAGLOBAL P/N 2006 0850 - Assembly Procedure

01. Excise a pre determined number of display substrates from a strip.

02. Inspect the individual displays to assure all circuits have mechanical integrity and are bondable

03. Remove any spurious dielectric material from bond sites.

04. Review placement scheme of individual diodes in substrate

05. Check and confirm integrity of bonding tool and assure bonding tool surface is 2.68 inches from base plate

06. Affix display substrate to 0.25 inch glass plate using high temperature tape

07. Place diode over cavity and inject the component in the cavity with insertion tool.

08. Proceed with the insertion process until 42 diodes have been placed

09. Prepare silver conductive ink for application on substrate

10. Use a wire stylus to apply a small amount of conductive material to each via site. Conductive material should be applied to the via site in a way that does not entirely fill the cavity but establishes continuity from top to bottom plate (page 01)

11. Place assembled parts in an oven and cure for 20 minutes at 168°C (325°F)

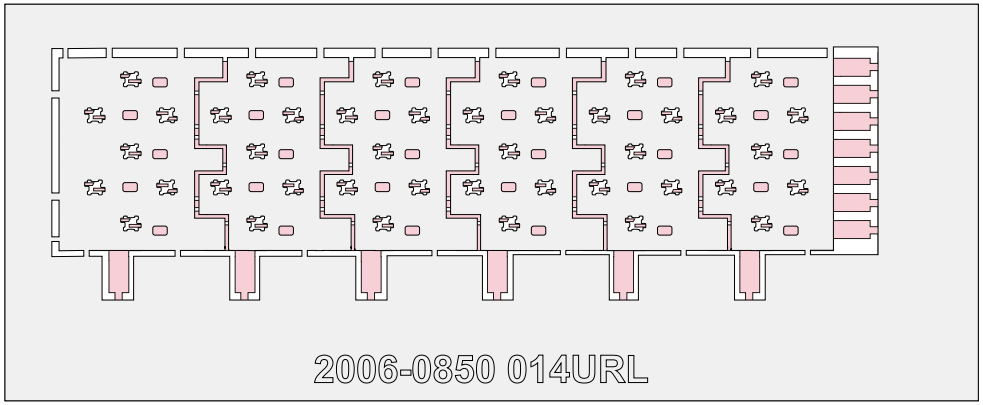
12. Remove from oven and affirm the parts are thoroughly cured by checking top to bottom continuity with an ohm meter

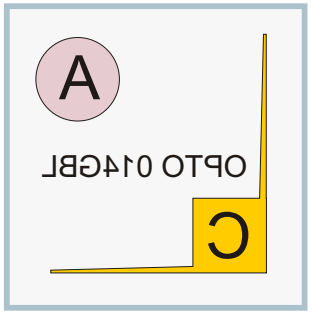
13. Perform a bond test. Adjust the voltage output on the power supply to 1.5V. Place the power probes on the anode and cathode bus bar of the display. Determine which bond sites are not connected and repair

14. Prepare the UV conformal coating material for application

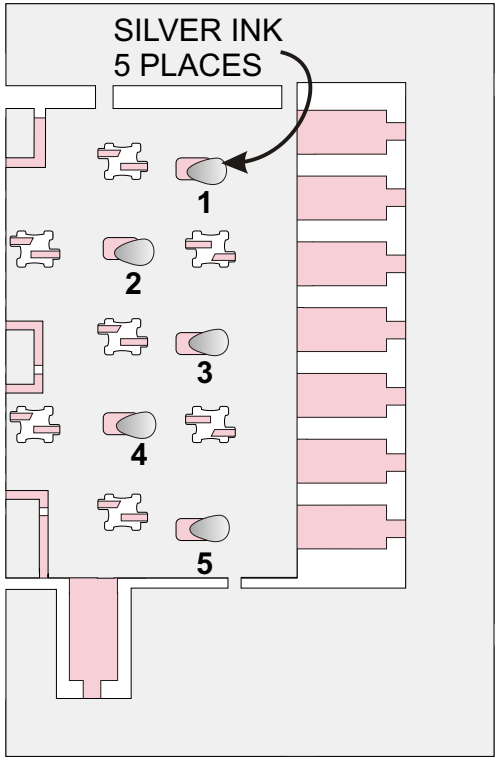
15. Use a wire stylus to impregnate the circuit side of the bonding site with coating material. The entire surface area of the diode should be completely coated. The meniscus of the coating material should be less than 10µm. (page 04)

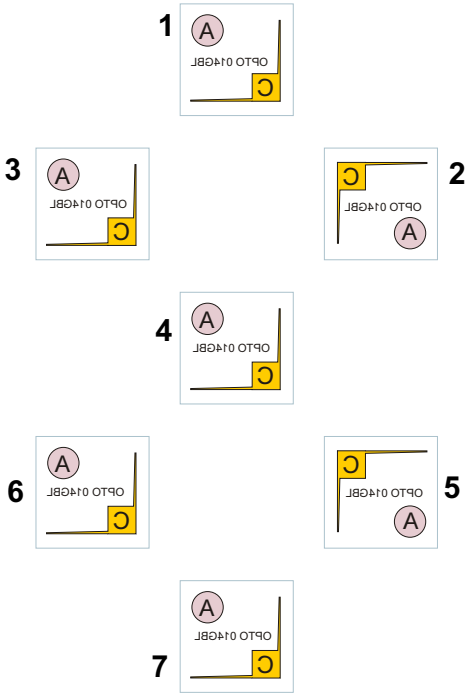
16. The manual assembly procedure is complete

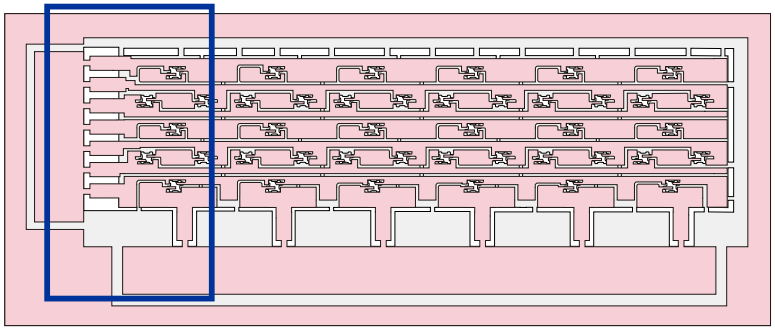


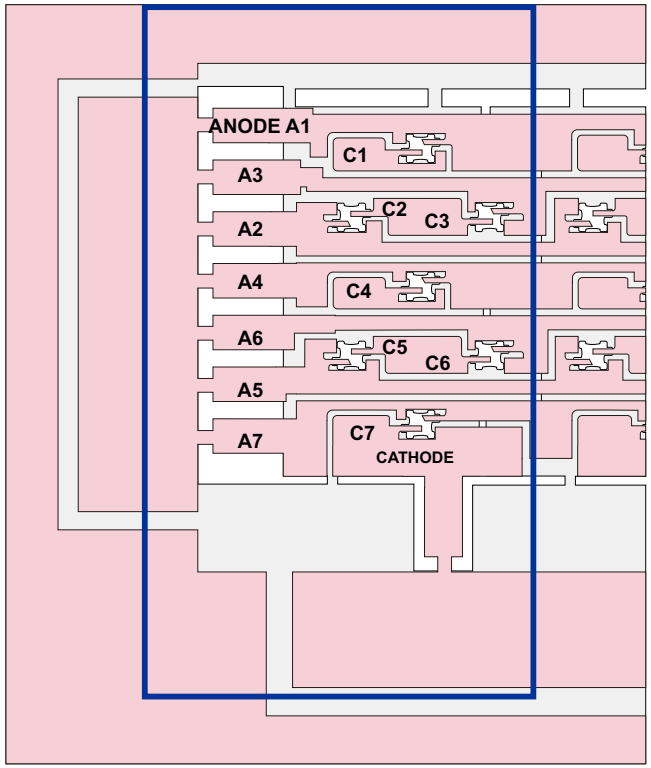


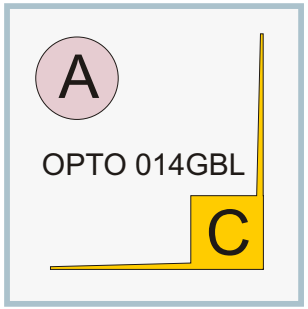
LOAD SIDE LOOKING
THRU THE DIODE











TOP SIDE LOOKING
AT THE PADS